

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

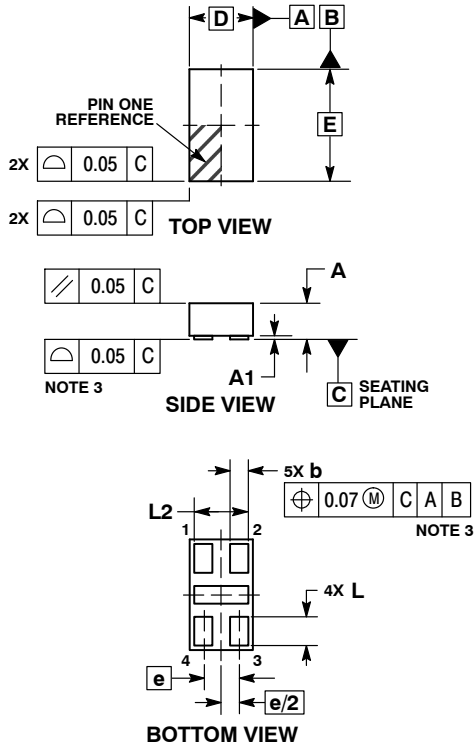
ON Semiconductor®



SCALE 8:1

X3DFN4 0.525x0.925, 0.3P
CASE 714AA
ISSUE B

DATE 08 DEC 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.24	0.32
A1	0.00	0.05
b	0.12	0.18
D	0.525 BSC	
E	0.925 BSC	
e	0.30 BSC	
L	0.173	0.233
L2	0.42	0.48

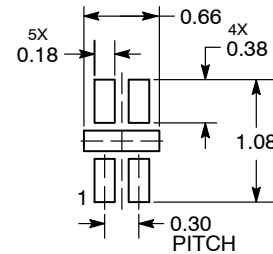
GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

RECOMMENDED SOLDER FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	X3DFN4 0.525X0.925, 0.3P	PAGE 1 OF 1

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